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Guidelines for Packing and Labeling of Integrated Circuits in Unit Container Packing (Tubes, Trays, and Tape and Reel)

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GUIDELINES FOR PACKING AND LABELING OF INTEGRATED CIRCUITS IN UNIT CONTAINER PACKING (TUBES, TRAYS, AND TAPE AND REEL)

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(From JEDEC Board Ballot JCB-16-44, formulated under the cognizance of JC-14.4 Subcommittee on Quality Processes and Methods.)

1 Scope

This document establishes the guidelines for unit container packing of integrated circuits and for the next level of container.

2 Terms and definitions

AUP: Average Unit Price

Intermediate Package Container: Product Package Container (ie: bag, box, reel) that holds 1 or more Unit Packs (see Unit Pack Container).

Unit Pack container: A first level wrap or containment of parts (ie; Tube, Tray, or Tape and Reel).

Date code: Marking on device package that usually indicates device final seal or encapsulation date.

PDIP: Plastic Dual-in-line package

PLCC: Plastic Leaded Chip Carrier

PLCCR: Rectangular PLCC

QFN (MLF): Plastic Quad Flat No-lead package (Plastic Micro Lead Frame Package)

SON: Plastic Dual Flat No-lead package (Plastic Dual Micro Lead Frame Package)

SOIC: Plastic Small Outline Package

SSOP: Plastic Shrink Small Outline Package

PSOP: Power Small Outline Plastic Package

TSSOP: Plastic Thin Small Outline Package

MSOP: Plastic Mini Small Outline Package

QSOP: Plastic Quad Small Outline Package

PQCC: Plastic Leadless Package

PQFP: Plastic Quad Flat pack Package

PBGA: Plastic Ball grid Array Package

2 Terms and definitions (cont'd)

CDIP: Ceramic Dual-In-Line (Metal Seal) Package

GDIP: Ceramic Dual-In-line (Glass Seal Package)

CPGA: Ceramic Pin Grid Array Package

CLCC: Ceramic Leadless Chip Carrier

3 Reference documents

The following documents are related reference sources.

CEA 556, *Outer Shipping Container Bar Code Label Standard*

EIA 541, *Packaging Material Standards for ESD Sensitive Items*

CEA 624, *Product Package Bar Code label Standard for Non-Retail Applications*

JEP95, *JEDEC Registered And Standard Outlines For Solid State And Related Products*

JESD30, *Descriptive Designation System for Semiconductor-Device Packages*

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